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	DMENT 7				M4065	.0014/P014
Application No.		Filing Date		Examiner		Art Unit
09/940,791		August 29, 2001		Kiesha L. Rose		2022
olicant(s): Larr	y D. Kinsman				···	
ention: LOW P	ROFILE BALL	GRID ARRAY	PACKAGE			
	TC	THE COMMI	SSIONER FO	OR PATENTS		
ansmitted here	with is an ame	ndment in the	above-identif	ied application.		
ne fee has been	calculated an	d is transmitte	d as shown b	elow.		
		CLAIM	S AS AMEN	DED		
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate		
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x No additiona	ıl fee is require	d for this ame	ndment.	_		
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as described	i below. A dup	licate copy of	this sheet is t	enciosea.		

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April 17, 2003

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Dated: ___

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Docket No.: M4065.0014/P014-B (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Larry D. Kinsman

Application No.: 09/940,791

Filed: August 29, 2001

For: LOW PROFILE BALL GRID ARRAY

PACKAGE

Examiner: Kiesha L. Rose

Group Art Unit: 2822

AMENDMENT

DX: Non-Fee Amenan.

ommissioner for Patents
/ashington, DC 20231

Dear Sir:

This paper is in response to the Office Action of January 21, 2003, reject.

claims 39-45, please amend the above-identified U.S. patent application as follows:

IN THE CLAIMS:

29 42 and 45 as follows:

a central processing unit; and

a memory device connected to said central processing unit, said memory device comprised of a plurality of low profile ball grid array semiconductor packages, said low profile ball grid array semiconductor packages comprised of a base substrate having a top surface and a bottom surface, with an aperture therein which extends from said top surface to said bottom surface,

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